

November 1997 - Revised October 2003

## High-Speed CMOS Logic 9-Bit Odd/Even Parity Generator/Checker

### Features

- Typical Propagation Delay = 17ns at  $V_{CC} = 5V$ ,  $C_L = 15pF$ ,  $T_A = 25^{\circ}C$
- Replaces LS180 Types
- Easily Cascadable
- Fanout (Over Temperature Range)
  - Standard Outputs . . . . . 10 LSTTL Loads
  - Bus Driver Outputs . . . . . 15 LSTTL Loads
- Wide Operating Temperature Range . . .  $-55^{\circ}C$  to  $125^{\circ}C$
- Balanced Propagation Delay and Transition Times
- Significant Power Reduction Compared to LSTTL Logic ICs
- HC Types
  - 2V to 6V Operation
  - High Noise Immunity:  $N_{IL} = 30\%$ ,  $N_{IH} = 30\%$  of  $V_{CC}$  at  $V_{CC} = 5V$
- HCT Types
  - 4.5V to 5.5V Operation
  - Direct LSTTL Input Logic Compatibility,  $V_{IL} = 0.8V$  (Max),  $V_{IH} = 2V$  (Min)
  - CMOS Input Compatibility,  $I_I \leq 1\mu A$  at  $V_{OL}$ ,  $V_{OH}$

### Description

The 'HC280 and 'HCT280 are 9-bit odd/even parity, generator checker devices. Both even and odd parity outputs are available for checking or generating parity for words up to nine bits long. Even parity is indicated ( $\Sigma E$  output is high) when an even number of data inputs is high. Odd parity is indicated ( $\Sigma O$  output is high) when an odd number of data inputs is high. Parity checking for words larger than 9 bits can be accomplished by tying the  $\Sigma E$  output to any input of an additional HC/HCT280 parity checker.

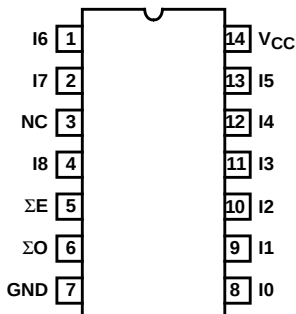
### Ordering Information

| PART NUMBER   | TEMP. RANGE<br>( $^{\circ}C$ ) | PACKAGE      |
|---------------|--------------------------------|--------------|
| CD54HC280F3A  | -55 to 125                     | 14 Ld Cerdip |
| CD54HCT280F3A | -55 to 125                     | 14 Ld Cerdip |
| CD74HC280E    | -55 to 125                     | 14 Ld PDIP   |
| CD74HC280MT   | -55 to 125                     | 14 Ld SOIC   |
| CD74HC280M96  | -55 to 125                     | 14 Ld SOIC   |
| CD74HCT280E   | -55 to 125                     | 14 Ld PDIP   |

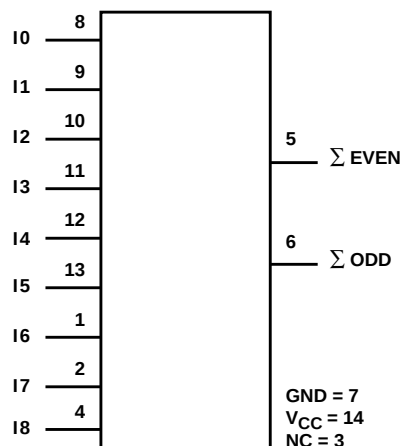
NOTE: When ordering, use the entire part number. The suffix 96 denotes tape and reel. The suffix T denotes a small-quantity reel of 250.

### Pinout

CD54HC280, CD54HCT280  
(CERDIP)  
CD74HC280  
(PDIP, SOIC)  
CD74HCT280  
(PDIP)  
TOP VIEW



### Functional Diagram



# CD54HC280, CD74HC280, CD54HCT280, CD74HCT280

## Absolute Maximum Ratings

DC Supply Voltage,  $V_{CC}$  ..... -0.5V to 7V  
 DC Input Diode Current,  $I_{IK}$   
 For  $V_I < -0.5V$  or  $V_I > V_{CC} + 0.5V$  .....  $\pm 20mA$   
 DC Output Diode Current,  $I_{OK}$   
 For  $V_O < -0.5V$  or  $V_O > V_{CC} + 0.5V$  .....  $\pm 20mA$   
 DC Drain Current, per Output,  $I_O$   
 For  $-0.5V < V_O < V_{CC} + 0.5V$  .....  $\pm 25mA$   
 DC Output Source or Sink Current per Output Pin,  $I_O$   
 For  $V_O > -0.5V$  or  $V_O < V_{CC} + 0.5V$  .....  $\pm 25mA$   
 DC  $V_{CC}$  or Ground Current,  $I_{CC}$  .....  $\pm 50mA$

## Thermal Information

Thermal Resistance (Typical, Note1)  $\theta_{JA}$  ( $^{\circ}C/W$ )  
 E (PDIP) Package ..... 80  
 M (SOIC) Package ..... 86  
 Maximum Junction Temperature .....  $150^{\circ}C$   
 Maximum Storage Temperature Range .....  $-65^{\circ}C$  to  $150^{\circ}C$   
 Maximum Lead Temperature (Soldering 10s) .....  $300^{\circ}C$   
 (SOIC - Lead Tips Only)

## Operating Conditions

Temperature Range,  $T_A$  .....  $-55^{\circ}C$  to  $125^{\circ}C$   
 Supply Voltage Range,  $V_{CC}$   
 HC Types ..... 2V to 6V  
 HCT Types ..... 4.5V to 5.5V  
 DC Input or Output Voltage,  $V_I$ ,  $V_O$  ..... 0V to  $V_{CC}$   
 Input Rise and Fall Time  
 2V ..... 1000ns (Max)  
 4.5V ..... 500ns (Max)  
 6V ..... 400ns (Max)

**CAUTION:** Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

NOTE:

1. The package thermal impedance is calculated in accordance with JESD 51-7.

## DC Electrical Specifications

| PARAMETER                               | SYMBOL          | TEST CONDITIONS                       |                     | V <sub>CC</sub> (V) | 25°C |     |      | -40°C TO 85°C |      | -55°C TO 125°C |      | UNITS |  |
|-----------------------------------------|-----------------|---------------------------------------|---------------------|---------------------|------|-----|------|---------------|------|----------------|------|-------|--|
|                                         |                 | V <sub>I</sub> (V)                    | I <sub>O</sub> (mA) |                     | MIN  | TYP | MAX  | MIN           | MAX  | MIN            | MAX  |       |  |
| HC TYPES                                |                 |                                       |                     |                     |      |     |      |               |      |                |      |       |  |
| High Level Input Voltage                | V <sub>IH</sub> | -                                     | -                   | 2                   | 1.5  | -   | -    | 1.5           | -    | 1.5            | -    | V     |  |
|                                         |                 |                                       |                     | 4.5                 | 3.15 | -   | -    | 3.15          | -    | 3.15           | -    | V     |  |
|                                         |                 |                                       |                     | 6                   | 4.2  | -   | -    | 4.2           | -    | 4.2            | -    | V     |  |
| Low Level Input Voltage                 | V <sub>IL</sub> | -                                     | -                   | 2                   | -    | -   | 0.5  | -             | 0.5  | -              | 0.5  | V     |  |
|                                         |                 |                                       |                     | 4.5                 | -    | -   | 1.35 | -             | 1.35 | -              | 1.35 | V     |  |
|                                         |                 |                                       |                     | 6                   | -    | -   | 1.8  | -             | 1.8  | -              | 1.8  | V     |  |
| High Level Output Voltage<br>CMOS Loads | V <sub>OH</sub> | V <sub>IH</sub> or<br>V <sub>IL</sub> | -0.02               | 2                   | 1.9  | -   | -    | 1.9           | -    | 1.9            | -    | V     |  |
|                                         |                 |                                       | -0.02               | 4.5                 | 4.4  | -   | -    | 4.4           | -    | 4.4            | -    | V     |  |
|                                         |                 |                                       | -0.02               | 6                   | 5.9  | -   | -    | 5.9           | -    | 5.9            | -    | V     |  |
| High Level Output Voltage<br>TTL Loads  |                 |                                       | -4                  | 4.5                 | 3.98 | -   | -    | 3.84          | -    | 3.7            | -    | V     |  |
|                                         |                 |                                       | -5.2                | 6                   | 5.48 | -   | -    | 5.34          | -    | 5.2            | -    | V     |  |
| Low Level Output Voltage<br>CMOS Loads  | V <sub>OL</sub> | V <sub>IH</sub> or<br>V <sub>IL</sub> | 0.02                | 2                   | -    | -   | 0.1  | -             | 0.1  | -              | 0.1  | V     |  |
|                                         |                 |                                       | 0.02                | 4.5                 | -    | -   | 0.1  | -             | 0.1  | -              | 0.1  | V     |  |
|                                         |                 |                                       | 0.02                | 6                   | -    | -   | 0.1  | -             | 0.1  | -              | 0.1  | V     |  |
| Low Level Output Voltage<br>TTL Loads   |                 |                                       | 4                   | 4.5                 | -    | -   | 0.26 | -             | 0.33 | -              | 0.4  | V     |  |
|                                         |                 |                                       | 5.2                 | 6                   | -    | -   | 0.26 | -             | 0.33 | -              | 0.4  | V     |  |
| Input Leakage Current                   | I <sub>I</sub>  | V <sub>CC</sub> or GND                | -                   | 6                   | -    | -   | ±0.1 | -             | ±1   | -              | ±1   | μA    |  |
| Quiescent Device Current                | I <sub>CC</sub> | V <sub>CC</sub> or GND                | 0                   | 6                   | -    | -   | 8    | -             | 80   | -              | 160  | μA    |  |

**CD54HC280, CD74HC280, CD54HCT280, CD74HCT280**

**DC Electrical Specifications** (Continued)

| PARAMETER                                                      | SYMBOL                    | TEST CONDITIONS                    |                     | V <sub>CC</sub> (V) | 25°C |     |      | -40°C TO 85°C |      | -55°C TO 125°C |     | UNITS |
|----------------------------------------------------------------|---------------------------|------------------------------------|---------------------|---------------------|------|-----|------|---------------|------|----------------|-----|-------|
|                                                                |                           | V <sub>I</sub> (V)                 | I <sub>O</sub> (mA) |                     | MIN  | TYP | MAX  | MIN           | MAX  | MIN            | MAX |       |
| HCT TYPES                                                      |                           |                                    |                     |                     |      |     |      |               |      |                |     |       |
| High Level Input Voltage                                       | V <sub>IH</sub>           | -                                  | -                   | 4.5 to 5.5          | 2    | -   | -    | 2             | -    | 2              | -   | V     |
| Low Level Input Voltage                                        | V <sub>IL</sub>           | -                                  | -                   | 4.5 to 5.5          | -    | -   | 0.8  | -             | 0.8  | -              | 0.8 | V     |
| High Level Output Voltage<br>CMOS Loads                        | V <sub>OH</sub>           | V <sub>IH</sub> or V <sub>IL</sub> | -0.02               | 4.5                 | 4.4  | -   | -    | 4.4           | -    | 4.4            | -   | V     |
| High Level Output Voltage<br>TTL Loads                         |                           |                                    | -4                  | 4.5                 | 3.98 | -   | -    | 3.84          | -    | 3.7            | -   | V     |
| Low Level Output Voltage<br>CMOS Loads                         | V <sub>OL</sub>           | V <sub>IH</sub> or V <sub>IL</sub> | 0.02                | 4.5                 | -    | -   | 0.1  | -             | 0.1  | -              | 0.1 | V     |
| Low Level Output Voltage<br>TTL Loads                          |                           |                                    | 4                   | 4.5                 | -    | -   | 0.26 | -             | 0.33 | -              | 0.4 | V     |
| Input Leakage Current                                          | I <sub>I</sub>            | V <sub>CC</sub> to GND             | 0                   | 5.5                 | -    | -   | ±0.1 | -             | ±1   | -              | ±1  | μA    |
| Quiescent Device Current                                       | I <sub>CC</sub>           | V <sub>CC</sub> or GND             | 0                   | 5.5                 | -    | -   | 8    | -             | 80   | -              | 160 | μA    |
| Additional Quiescent Device Current Per Input Pin: 1 Unit Load | ΔI <sub>CC</sub> (Note 2) | V <sub>CC</sub> -2.1               | -                   | 4.5 to 5.5          | -    | 100 | 360  | -             | 450  | -              | 490 | μA    |

NOTE:

2. For dual-supply systems theoretical worst case (V<sub>I</sub> = 2.4V, V<sub>CC</sub> = 5.5V) specification is 1.8mA.

**HCT Input Loading Table**

| INPUT | UNIT LOADS |
|-------|------------|
| All   | 1          |

NOTE: Unit Load is ΔI<sub>CC</sub> limit specified in DC Electrical Specifications table, e.g., 360μA max at 25°C.

**Switching Specifications** Input t<sub>r</sub>, t<sub>f</sub> = 6ns

| PARAMETER                             | SYMBOL                              | TEST<br>CONDITIONS    | V <sub>CC</sub> (V) | 25°C |     | -40°C TO 85°C | -55°C TO 125°C | UNITS |
|---------------------------------------|-------------------------------------|-----------------------|---------------------|------|-----|---------------|----------------|-------|
|                                       |                                     |                       |                     | TYP  | MAX | MAX           | MAX            |       |
| HC TYPES                              |                                     |                       |                     |      |     |               |                |       |
| Propagation Delay,<br>Any Input to ΣO | t <sub>PLH</sub> , t <sub>PHL</sub> | C <sub>L</sub> = 50pF | 2                   | -    | 200 | 250           | 300            | ns    |
|                                       |                                     |                       | 4.5                 | -    | 40  | 50            | 60             | ns    |
|                                       |                                     |                       | 6                   | -    | 34  | 43            | 51             | ns    |
|                                       |                                     | C <sub>L</sub> = 15pF | 5                   | 17   | -   | -             | -              | ns    |
| Propagation Delay,<br>Any Input to ΣE | t <sub>PLH</sub> , t <sub>PHL</sub> | C <sub>L</sub> = 50pF | 2                   | -    | 200 | 250           | 300            | ns    |
|                                       |                                     |                       | 4.5                 | -    | 40  | 50            | 60             | ns    |
|                                       |                                     |                       | 6                   | -    | 34  | 43            | 51             | ns    |
|                                       |                                     | C <sub>L</sub> = 15pF | 5                   | 17   | -   | -             | -              | ns    |

# **CD54HC280, CD74HC280, CD54HCT280, CD74HCT280**

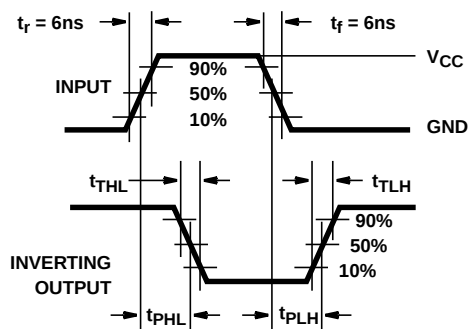
## **Switching Specifications** Input $t_r, t_f = 6\text{ns}$ (Continued)

| PARAMETER                                  | SYMBOL             | TEST CONDITIONS     | $V_{CC}$ (V) | 25°C |     | -40°C TO 85°C | -55°C TO 125°C | UNITS |
|--------------------------------------------|--------------------|---------------------|--------------|------|-----|---------------|----------------|-------|
|                                            |                    |                     |              | TYP  | MAX | MAX           | MAX            |       |
| Output Transition Time                     | $t_{TLH}, t_{THL}$ | $C_L = 50\text{pF}$ | 2            | -    | 75  | 95            | 110            | ns    |
|                                            |                    |                     | 4.5          | -    | 15  | 19            | 22             | ns    |
|                                            |                    |                     | 6            | -    | 13  | 16            | 19             | ns    |
| Input Capacitance                          | $C_I$              | -                   | -            | -    | 10  | 10            | 10             | pF    |
| Power Dissipation Capacitance (Notes 3, 4) | $C_{PD}$           | -                   | 5            | 58   | -   | -             | -              | pF    |
| <b>HCT TYPES</b>                           |                    |                     |              |      |     |               |                |       |
| Propagation Delay, Any Input to $\Sigma O$ | $t_{PLH}, t_{PHL}$ | $C_L = 50\text{pF}$ | 4.5          | -    | 45  | 56            | 68             | ns    |
|                                            |                    | $C_L = 15\text{pF}$ | 5            | 19   | -   | -             | -              | ns    |
| Propagation Delay, Any Input to $\Sigma E$ | $t_{PLH}, t_{PHL}$ | $C_L = 50\text{pF}$ | 4.5          | -    | 42  | 53            | 63             | ns    |
|                                            |                    | $C_L = 15\text{pF}$ | 5            | 18   | -   | -             | -              | ns    |
| Output Transition Time                     | $t_{TLH}, t_{THL}$ | $C_L = 50\text{pF}$ | 4.5          | -    | 15  | 19            | 22             | ns    |
| Input Capacitance                          | $C_{IN}$           | -                   | -            | -    | 10  | 10            | 10             | pF    |
| Power Dissipation Capacitance (Notes 3, 4) | $C_{PD}$           | -                   | 5            | 58   | -   | -             | -              | pF    |

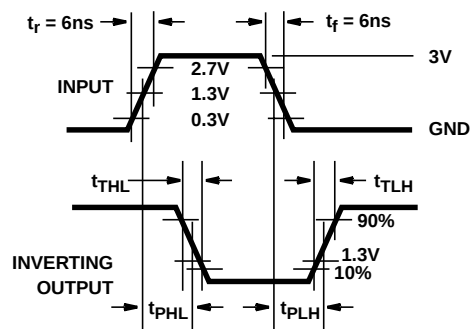
### NOTES:

- $C_{PD}$  is used to determine the dynamic power consumption, per package.
- $P_D = V_{CC}^2 f_i (C_{PD} + C_L)$  where  $f_i$  = Input Frequency,  $f_O$  = Output Frequency,  $C_L$  = Output Load Capacitance,  $V_{CC}$  = Supply Voltage.

## **Test Circuits and Waveforms**



**FIGURE 1. HC TRANSITION TIMES AND PROPAGATION DELAY TIMES, COMBINATION LOGIC**



**FIGURE 2. HCT TRANSITION TIMES AND PROPAGATION DELAY TIMES, COMBINATION LOGIC**

**PACKAGING INFORMATION**

| Orderable Device | Status <sup>(1)</sup> | Package Type | Package Drawing | Pins | Package Qty | Eco Plan <sup>(2)</sup>    | Lead/<br>Ball Finish | MSL Peak Temp <sup>(3)</sup> | Samples<br>(Requires Login) |
|------------------|-----------------------|--------------|-----------------|------|-------------|----------------------------|----------------------|------------------------------|-----------------------------|
| 8607701CA        | ACTIVE                | CDIP         | J               | 14   | 1           | TBD                        | Call TI              | Call TI                      |                             |
| CD54HC280F3A     | ACTIVE                | CDIP         | J               | 14   | 1           | TBD                        | A42                  | N / A for Pkg Type           |                             |
| CD54HCT280F3A    | ACTIVE                | CDIP         | J               | 14   | 1           | TBD                        | A42                  | N / A for Pkg Type           |                             |
| CD74HC280E       | ACTIVE                | PDIP         | N               | 14   | 25          | Pb-Free (RoHS)             | CU NIPDAU            | N / A for Pkg Type           |                             |
| CD74HC280EE4     | ACTIVE                | PDIP         | N               | 14   | 25          | Pb-Free (RoHS)             | CU NIPDAU            | N / A for Pkg Type           |                             |
| CD74HC280M96     | ACTIVE                | SOIC         | D               | 14   | 2500        | Green (RoHS<br>& no Sb/Br) | CU NIPDAU            | Level-1-260C-UNLIM           |                             |
| CD74HC280M96E4   | ACTIVE                | SOIC         | D               | 14   | 2500        | Green (RoHS<br>& no Sb/Br) | CU NIPDAU            | Level-1-260C-UNLIM           |                             |
| CD74HC280M96G4   | ACTIVE                | SOIC         | D               | 14   | 2500        | Green (RoHS<br>& no Sb/Br) | CU NIPDAU            | Level-1-260C-UNLIM           |                             |
| CD74HC280MT      | ACTIVE                | SOIC         | D               | 14   | 250         | Green (RoHS<br>& no Sb/Br) | CU NIPDAU            | Level-1-260C-UNLIM           |                             |
| CD74HC280MTE4    | ACTIVE                | SOIC         | D               | 14   | 250         | Green (RoHS<br>& no Sb/Br) | CU NIPDAU            | Level-1-260C-UNLIM           |                             |
| CD74HC280MTG4    | ACTIVE                | SOIC         | D               | 14   | 250         | Green (RoHS<br>& no Sb/Br) | CU NIPDAU            | Level-1-260C-UNLIM           |                             |
| CD74HCT280E      | ACTIVE                | PDIP         | N               | 14   | 25          | Pb-Free (RoHS)             | CU NIPDAU            | N / A for Pkg Type           |                             |
| CD74HCT280EE4    | ACTIVE                | PDIP         | N               | 14   | 25          | Pb-Free (RoHS)             | CU NIPDAU            | N / A for Pkg Type           |                             |

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBsolete:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

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**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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**OTHER QUALIFIED VERSIONS OF CD54HC280, CD54HCT280, CD74HC280, CD74HCT280 :**

- Catalog: [CD74HC280](#), [CD74HCT280](#)
- Military: [CD54HC280](#), [CD54HCT280](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

**TAPE AND REEL INFORMATION**
**REEL DIMENSIONS**

**TAPE DIMENSIONS**


|    |                                                           |
|----|-----------------------------------------------------------|
| A0 | Dimension designed to accommodate the component width     |
| B0 | Dimension designed to accommodate the component length    |
| K0 | Dimension designed to accommodate the component thickness |
| W  | Overall width of the carrier tape                         |
| P1 | Pitch between successive cavity centers                   |

**TAPE AND REEL INFORMATION**

\*All dimensions are nominal

| Device       | Package Type | Package Drawing | Pins | SPQ  | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|--------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| CD74HC280M96 | SOIC         | D               | 14   | 2500 | 330.0              | 16.4               | 6.5     | 9.0     | 2.1     | 8.0     | 16.0   | Q1            |
| CD74HC280MT  | SOIC         | D               | 14   | 250  | 330.0              | 16.4               | 6.5     | 9.0     | 2.1     | 8.0     | 16.0   | Q1            |

## TAPE AND REEL BOX DIMENSIONS



\*All dimensions are nominal

| Device       | Package Type | Package Drawing | Pins | SPQ  | Length (mm) | Width (mm) | Height (mm) |
|--------------|--------------|-----------------|------|------|-------------|------------|-------------|
| CD74HC280M96 | SOIC         | D               | 14   | 2500 | 367.0       | 367.0      | 38.0        |
| CD74HC280MT  | SOIC         | D               | 14   | 250  | 367.0       | 367.0      | 38.0        |

J (R-GDIP-T\*\*)

14 LEADS SHOWN

# CERAMIC DUAL IN-LINE PACKAGE



| PINS **<br>DIM | 14                     | 16                     | 18                     | 20                     |
|----------------|------------------------|------------------------|------------------------|------------------------|
| A              | 0.300<br>(7,62)<br>BSC | 0.300<br>(7,62)<br>BSC | 0.300<br>(7,62)<br>BSC | 0.300<br>(7,62)<br>BSC |
| B MAX          | 0.785<br>(19,94)       | .840<br>(21,34)        | 0.960<br>(24,38)       | 1.060<br>(26,92)       |
| B MIN          | —                      | —                      | —                      | —                      |
| C MAX          | 0.300<br>(7,62)        | 0.300<br>(7,62)        | 0.310<br>(7,87)        | 0.300<br>(7,62)        |
| C MIN          | 0.245<br>(6,22)        | 0.245<br>(6,22)        | 0.220<br>(5,59)        | 0.245<br>(6,22)        |



4040083/F 03/03

- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package is hermetically sealed with a ceramic lid using glass frit.
  - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
  - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

N (R-PDIP-T\*\*)

16 PINS SHOWN

## PLASTIC DUAL-IN-LINE PACKAGE



| PINS **<br>DIM      | 14               | 16               | 18               | 20               |
|---------------------|------------------|------------------|------------------|------------------|
| A MAX               | 0.775<br>(19,69) | 0.775<br>(19,69) | 0.920<br>(23,37) | 1.060<br>(26,92) |
| A MIN               | 0.745<br>(18,92) | 0.745<br>(18,92) | 0.850<br>(21,59) | 0.940<br>(23,88) |
| MS-001<br>VARIATION | AA               | BB               | AC               | AD               |



4040049/E 12/2002

NOTES:

- A. All linear dimensions are in inches (millimeters).  
B. This drawing is subject to change without notice.
-  Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).  
 The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Publication IPC-7351 is recommended for alternate designs.
  - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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|                        |                                                                                      |
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| DLP® Products          | <a href="http://www.dlp.com">www.dlp.com</a>                                         |
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| Interface              | <a href="http://interface.ti.com">interface.ti.com</a>                               |
| Logic                  | <a href="http://logic.ti.com">logic.ti.com</a>                                       |
| Power Mgmt             | <a href="http://power.ti.com">power.ti.com</a>                                       |
| Microcontrollers       | <a href="http://microcontroller.ti.com">microcontroller.ti.com</a>                   |
| RFID                   | <a href="http://www.ti-rfid.com">www.ti-rfid.com</a>                                 |
| OMAP Mobile Processors | <a href="http://www.ti.com/omap">www.ti.com/omap</a>                                 |
| Wireless Connectivity  | <a href="http://www.ti.com/wirelessconnectivity">www.ti.com/wirelessconnectivity</a> |

### Applications

|                               |                                                                                          |
|-------------------------------|------------------------------------------------------------------------------------------|
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| Consumer Electronics          | <a href="http://www.ti.com/consumer-apps">www.ti.com/consumer-apps</a>                   |
| Energy and Lighting           | <a href="http://www.ti.com/energy">www.ti.com/energy</a>                                 |
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